34. (Original) The method as claimed in claim 33, wherein the conductive material is applied on a second wiring line thereof spaced apart from the first wiring line in the step (b) so that the second wiring line has a third portion thicker than a fourth portion thereof.

35. (Original) A method of forming wiring lines on a board to form a printed circuit board, comprising the steps of:

(a) forming the wring lines of a predetermined uniform thickness; and

(b) grinding a first wiring line thereof so that the first wiring line has a first portion thinner than a second portion thereof.

C1

36. (Original) The method as claimed in claim 35, wherein a second wiring line thereof spaced apart from the first wiring line is ground in the step (b) so as to have a third portion thinner than a fourth portion thereof.

C2 37. (Amended) A method of forming a plurality of wiring lines of conductive material on a board <u>having a core layer</u> to form a printed circuit board, comprising:

(a) forming said plurality of wiring lines <u>on a surface of said core layer</u>, having first and second portions, ~~and a uniform thickness on the board~~ <u>the plurality of wiring lines formed on said surface of said core having a uniform thickness in height relative to said surface of said core layer</u>; and

(b) etching a first of said plurality of wiring lines, such that the first portion is thinner in height relative to said surface of said core layer than the second portion.

38. (Amended) The method as claimed in Claim 37, wherein a second of said plurality of said wiring lines is provided, spaced from said first wiring line of said plurality of wiring lines having said first and second portions, ~~the~~ said second wiring line having third and fourth portions, and etching ~~the~~ said second wiring line such that the third portion is thinner in height relative to said surface of said core layer than the fourth portion.